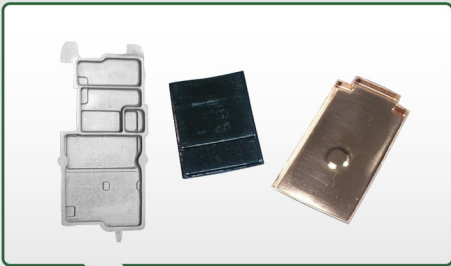


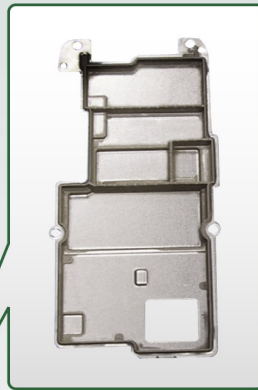
# Wireless Devices

## EMI Shielding

▼ Vacuum Forming Plastic Covers with PVD coating (VPCan)



▼ Mold-In-Place Gasket (MIPG)



▲ Camera Lens Holder/  
Physical Vapor  
Deposition (PVD)



▲ Conductive Elastomer



▲ Form-In-Place (FIPG)



▲ Physical Vapor  
Deposition (PVD)

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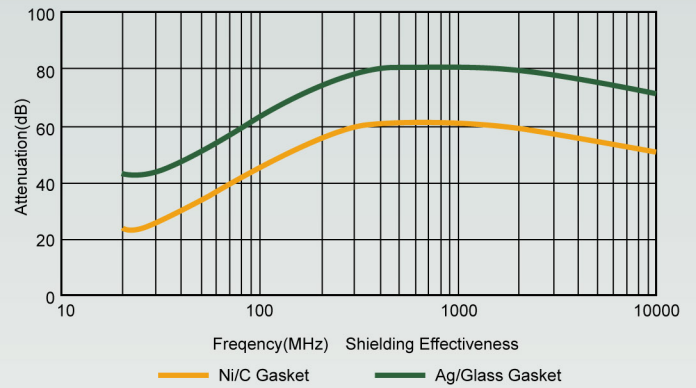
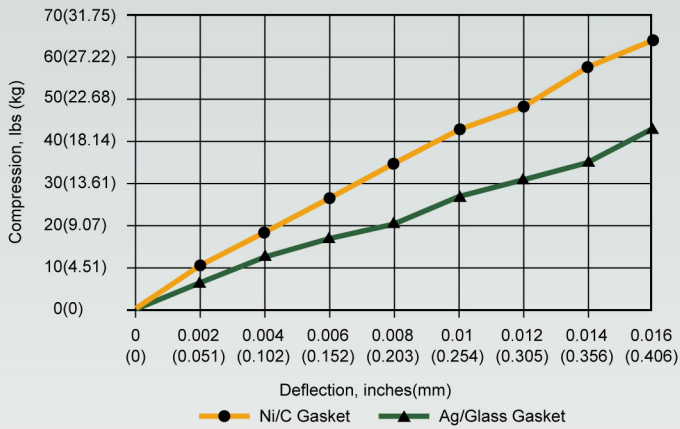
TennMax America

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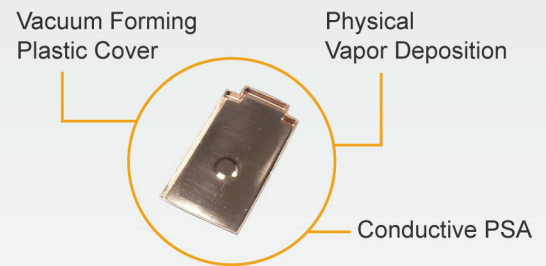
## ▼ Mold-In-Place Gasket (MIPG)



## ▼ Vacuum Forming Plastic Can (VPCan):

### ■ Construction:

Item	Materials	Feature	Applications
Vacuum Forming Plastic Cover	PC, PET...etc.	1. Low Cost 2. Short Tool time	1. Mobile Devices: Cell Phones, PDA. 2. Multi-Cavities required PCB
Physical Vapor Deposition (PVD)	Cu/NiCr	High Shielding Effectiveness	
Conductive PSA (Pressure Sensitive Adhesive)	Ag/Glass filled Silicone PSA	1. High reliability Adhesive 2. Easy installation 3. Reworkable	



## ▼ Physical Vapor Deposition (PVD)

Item	Materials	Feature	Applications
Substrate Selection	PC/ABS, PA66...etc.		
Metal Selection	Cu/NiCr	General	General Plastic Enclosures
	Al/CVD	Salt Spray Resistance 48 Hours	Automotive Devices
	Cu/Stainless Steel	Harder surface	Camera Holders
	Cu/Ni/Sn	Solderable	Heater, Antenna

